





Product Summary

V _{(BR)DSS}	R _{DS(on) max}	Ι _D Τ _A = +25°C
201/	0.4Ω @ $V_{GS} = 4.5V$	1A
20V	0.7 Ω @ V _{GS} = 1.8V	0.8A

Features and Benefits

- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)}, 1.0V Max.
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surfaced Mount Package
- Ultra-Low Package Profile, 0.4mm Maximum Package Height
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power Management Functions

Mechanical Data

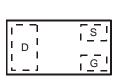
- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.001 grams (Approximate)



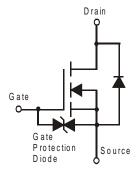




Bottom View



Top View Internal Schematic



EQUIVALENT CIRCUIT

Ordering Information (Note 3)

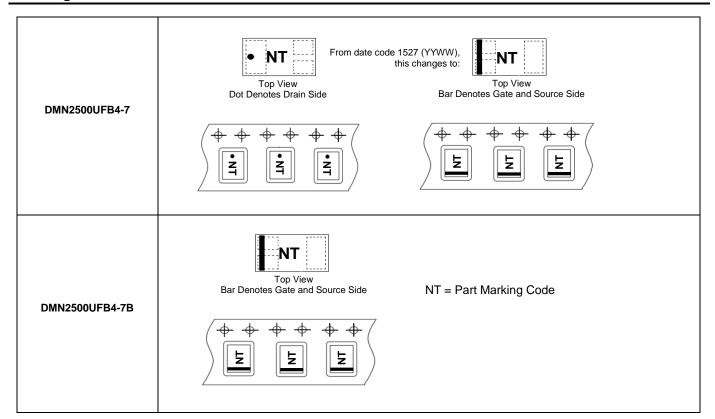
Part Number	Case	Packaging
DMN2500UFB4-7	X2-DFN1006-3	3,000/Tape & Reel
DMN2500UFB4-7B	X2-DFN1006-3	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.



Marking Information





Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V _{DSS}	20	V		
Gate-Source Voltage			V _{GSS}	±6	V
Continuous Dunis Courset (Nate A) V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	810 640	mA
Continuous Drain Current (Note 4) V _{GS} = 4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	950 750	mA
Continuous Dunis Coursest (Nata 5) V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	1000 800	mA
Continuous Drain Current (Note 5) V _{GS} = 4.5V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	1200 1000	mA
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	4	Α
Maximum Body Diode continuous Current			Is	850	mA

Thermal Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 4)	$T_A = +25^{\circ}C$	6	0.46	W
Total Power Dissipation (Note 4)	$T_A = +70^{\circ}C$	P_{D}	0.29	
Thormal Posistance, Junction to Ambient (Note 4)	Steady State	6	279	°C/W
Thermal Resistance, Junction to Ambient (Note 4)	t<10s	$R_{\theta JA}$	210	°C/W
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	C	0.95	W
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	P_{D}	0.6	
Thermal Peristance, Junction to Ambient (Note 5)	Steady State	6	134	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{ heta JA}$	100	°C/W
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C

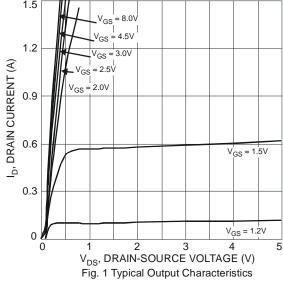
Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

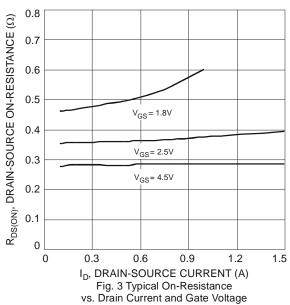
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	1	100	nA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±1.0	μA	$V_{GS} = \pm 4.5V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)	ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(th)}	0.5	-	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
			0.3	0.4	Ω	$V_{GS} = 4.5V, I_D = 600mA$	
Static Drain-Source On-Resistance	R _{DS} (ON)	-	0.4	0.5		$V_{GS} = 2.5V, I_D = 500mA$	
			0.5	0.7		$V_{GS} = 1.8V, I_D = 350mA$	
Forward Transfer Admittance	Y _{fs}	-	1.4	-	S	V _{DS} = 10V, I _D = 400mA	
Diode Forward Voltage	V _{SD}		0.7	1.2	V	V _{GS} = 0V, I _S = 150mA	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C _{iss}	-	60.67	-	pF	V _{DS} =16V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	-	9.68	-	pF		
Reverse Transfer Capacitance	C _{rss}	-	5.37	-	pF	-1 = 1.0Winz	
Gate resistance	Rg	-	93	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge	Qg	-	736.6	-	рС	1, 1,5), 1, 1,0),	
Gate-Source Charge	Qgs	-	93.6	-	рС	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 250mA$	
Gate-Drain Charge	Q_{gd}	-	116.6	-	рC		
Turn-On Delay Time	t _{D(on)}	-	5.1	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_{L} = 47\Omega, R_{G} = 10\Omega,$ $I_{D} = 200 \text{mA}$	
Turn-On Rise Time	t _r	-	7.4	-	ns		
Turn-Off Delay Time	t _{D(off)}	-	26.7	-	ns		
Turn-Off Fall Time	t _f	-	12.3	-	ns		

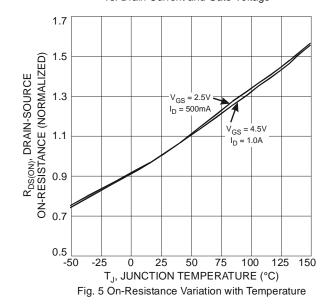
4. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate. Notes:

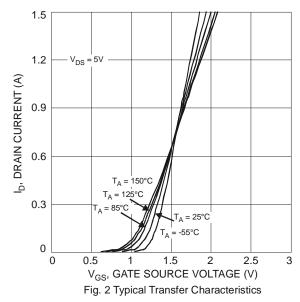
Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.











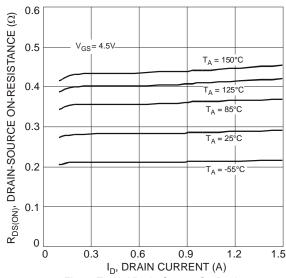


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

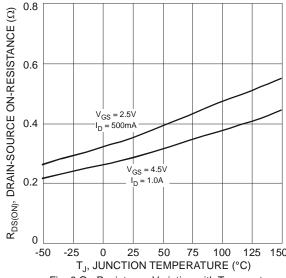


Fig. 6 On-Resistance Variation with Temperature



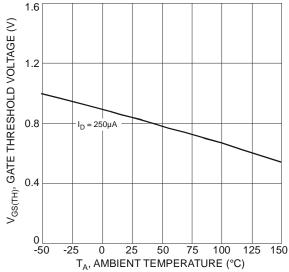
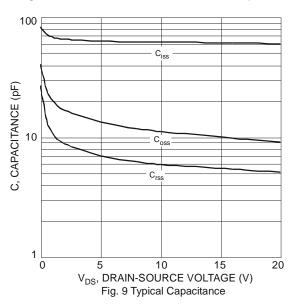
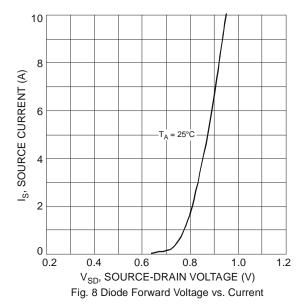
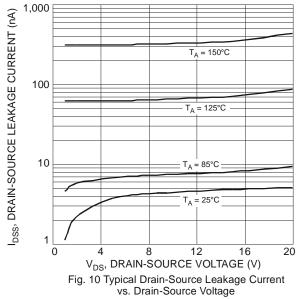


Fig. 7 Gate Threshold Variation vs. Ambient Temperature



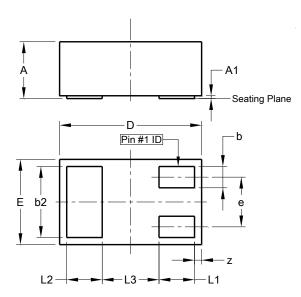






Package Outline Dimensions

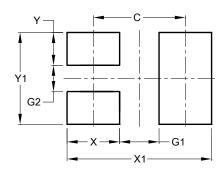
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X2-DFN1006-3					
Dim	Min	Max	Тур		
Α	-	0.40			
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.05	1.00		
Е	0.55	0.65	0.60		
е	-	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	ı	ı	0.40		
z	0.02	0.08	0.05		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Υ	0.25
Y1	0.70



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